



1SV263 Silicon Epitaxial Type Pin Diode for VHF, UHF, AGC Applications

Features

- Ultrasmall-sized package facilitates high-density mounting and permits 1SV263-applied equipment to be made smaller
- Small interterminal capacitance ($C=0.23\text{pF}$ typ)
- Small forward series resistance ($r_s=2.5\Omega$ typ)

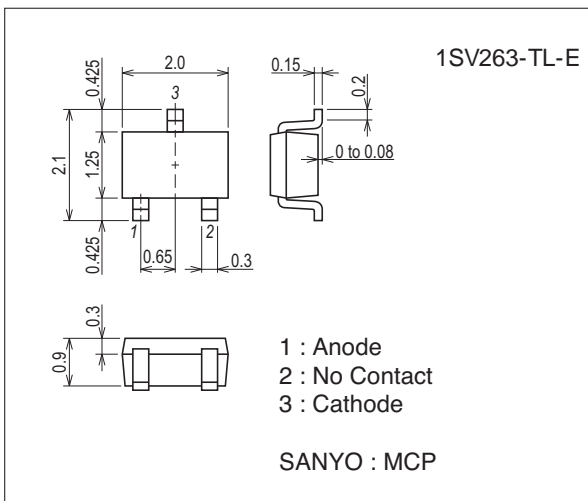
Specifications

Absolute Maximum Ratings at $T_a=25^\circ\text{C}$

Parameter	Symbol	Conditions	Ratings	Unit
Reverse Voltage	V_R		50	V
Forward Current	I_F		50	mA
Allowable Power Dissipation	P		100	mW
Junction Temperature	T_j		125	$^\circ\text{C}$
Storage Temperature	T_{stg}		-55 to +125	$^\circ\text{C}$

Package Dimensions

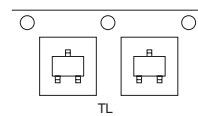
unit : mm (typ)
7023A-005



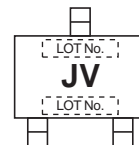
Product & Package Information

- Package : MCP
- JEITA, JEDEC : SC-70, SOT-323
- Minimum Packing Quantity : 3,000 pcs./reel

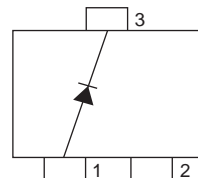
Packing Type: TL



Marking



Electrical Connection



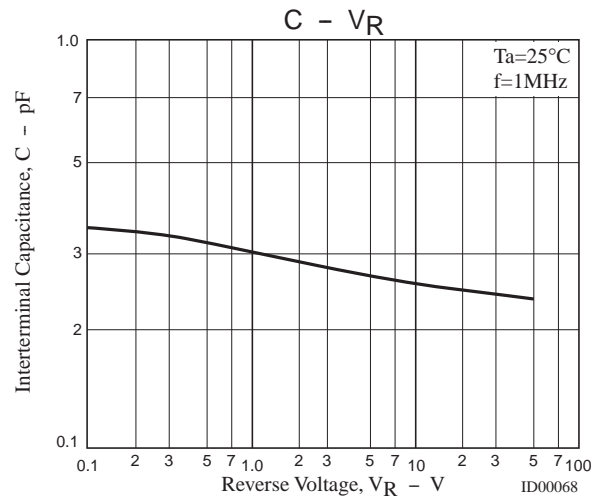
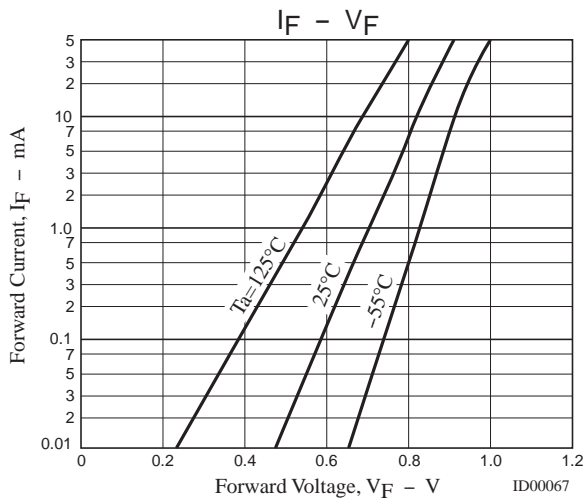
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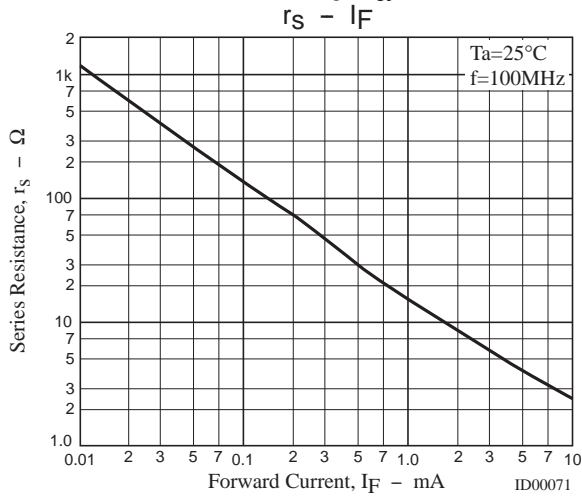
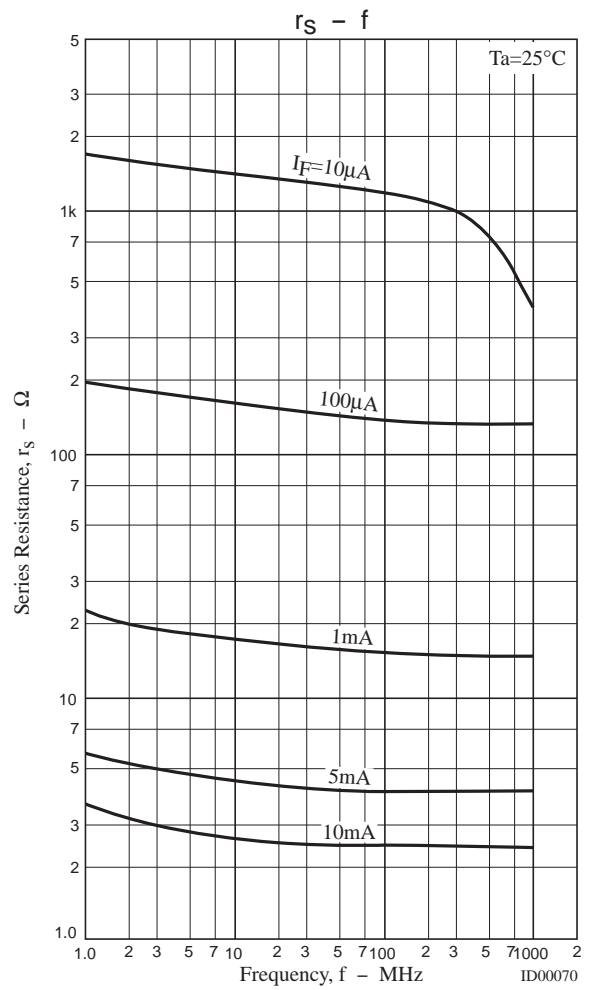
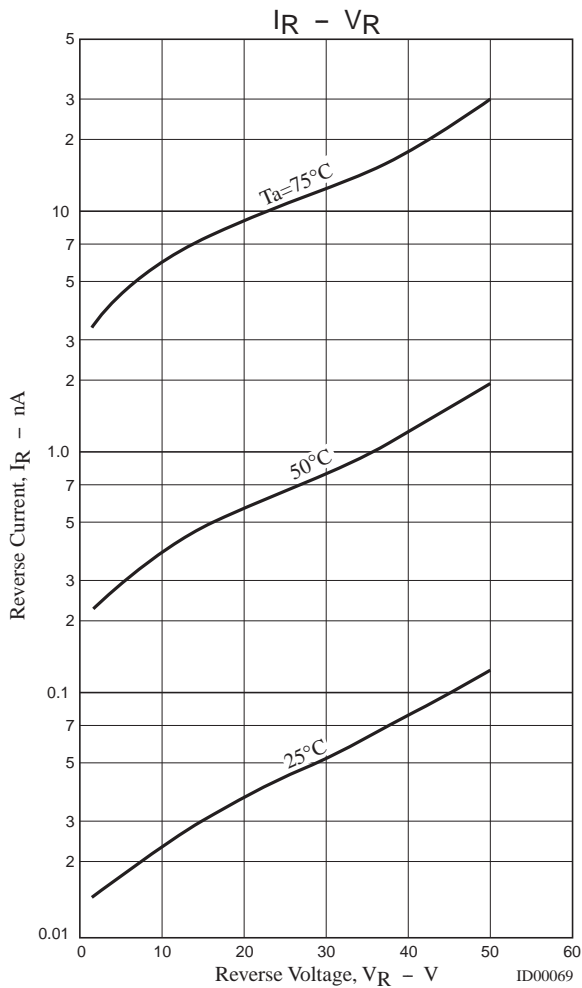
Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Reverse Voltage	V_R	$I_R=10\mu A$	50			V
Reverse Current	I_R	$V_R=50V$			0.1	μA
Forward Voltage	V_F	$I_F=50mA$		0.91	0.95	V
Interterminal Capacitance	C	$V_R=50V, f=1MHz$		0.23	0.4	pF
Series Resistance	r_s	$I_F=5mA, f=100MHz$		4.0	8.0	Ω
		$I_F=10mA, f=100MHz$		2.5	4.5	Ω

Ordering Information

Device	Package	Shipping	memo
1SV263-TL-E	MCP	3,000pcs./reel	Pb Free





Embossed Taping Specification

1SV263-TL-E

1. Packing Format

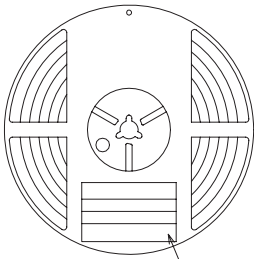
Package Name	Carrier Tape Type	Maximum Number of devices contained (pcs)			Packing format	
		Reel	Inner box	Outer box	Inner BOX (C-1)	Outer BOX (A-7)
MCP	MCP	3,000	15,000	90,000	5 reels contained Dimensions:mm (external) 183×72×185	6 inner boxes contained Dimensions:mm (external) 440×195×210

Reel label, Inner box label
(unit: mm)

Outer box label

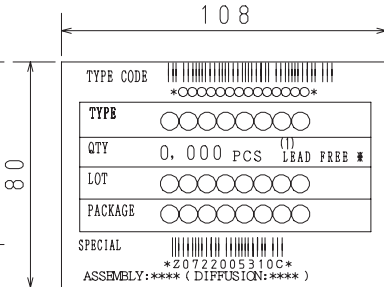
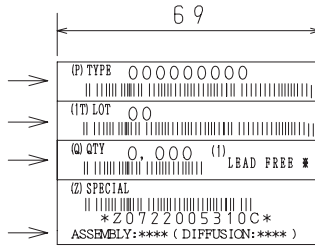
It is a label at the time of factory shipments.
The form of a label may change in physical distribution process.

Packing method



Reel label

Type No.
LOT No.
Quantity
Origin



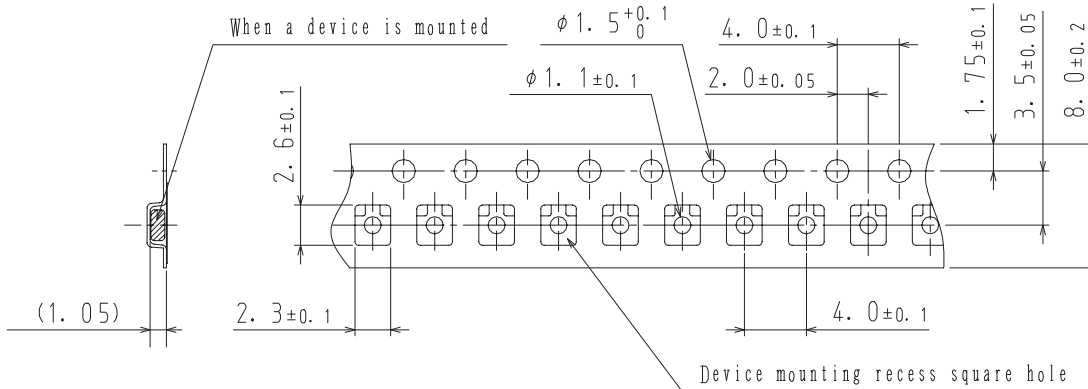
NOTE (1)

The LEAD FREE * description shows that the surface treatment of the terminal is lead free.

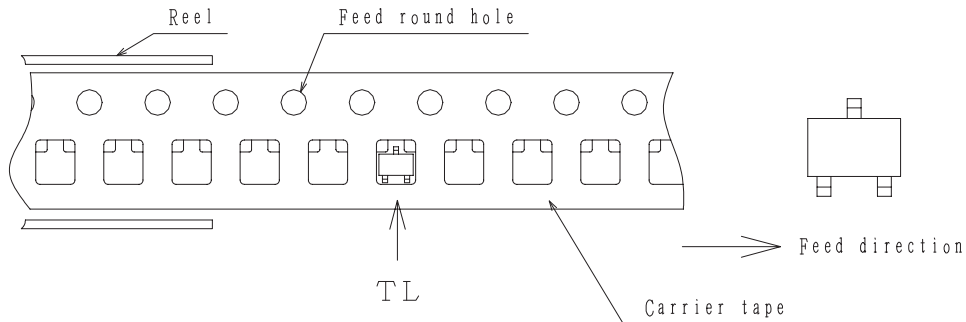
Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3

2. Taping configuration

2-1. Carrier tape size (unit:mm)



2-2. Device placement direction

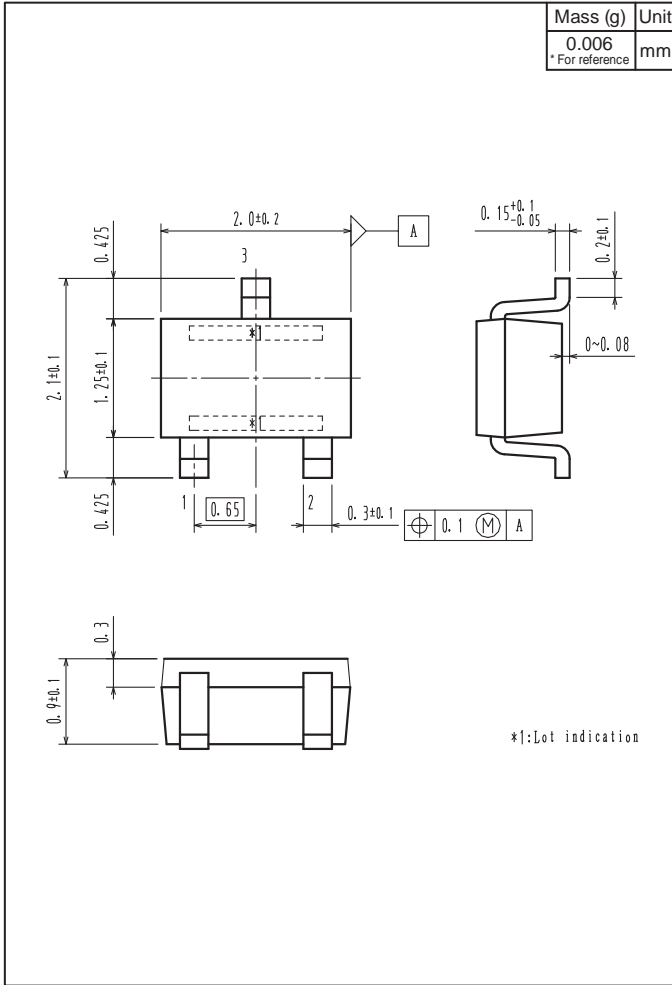


Those with oen electrode terminal on the feed hole side.....TL

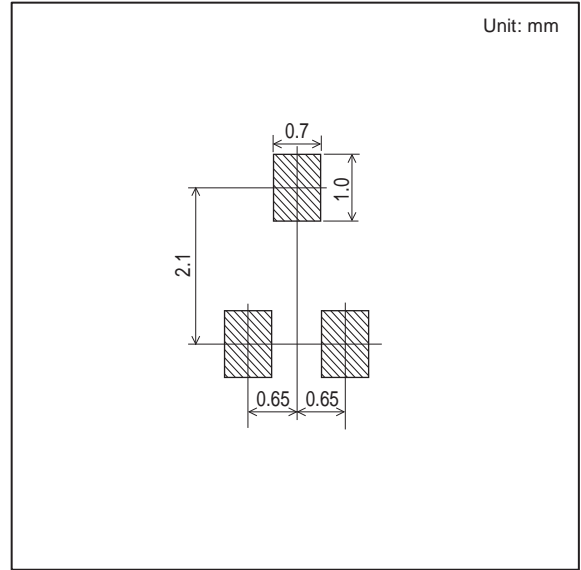
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Outline Drawing

1SV263-TL-E



Land Pattern Example



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